

描述 / Descriptions

SOT-23 塑封封装 N 沟道 MOS 场效应管。N-CHANNEL MOSFET in a SOT-23 Plastic Package.

特征 / Features

输出电阻小、性能高；SOT-23 封装，利于设计安装。

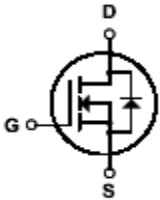
Low $R_{DS(on)}$, rugged and reliable, compact industry standard SOT-23 surface mount package.

用途 / Applications

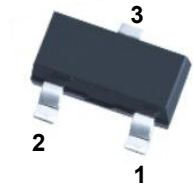
用于小电流伺服马达控制、功率 MOSFET 的门电压驱动及其它开关电路。

Low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN 1 : S PIN 2 : G PIN 3 : D

印章代码 / Marking

Marking	HSS
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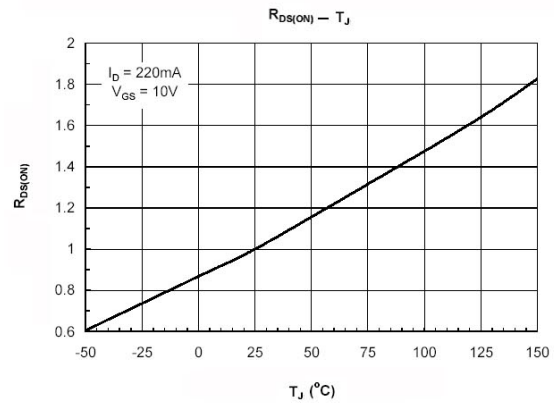
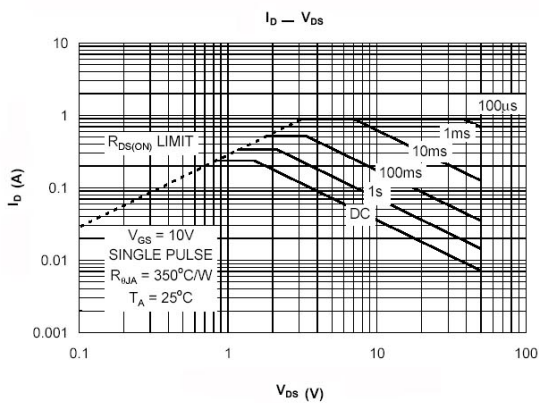
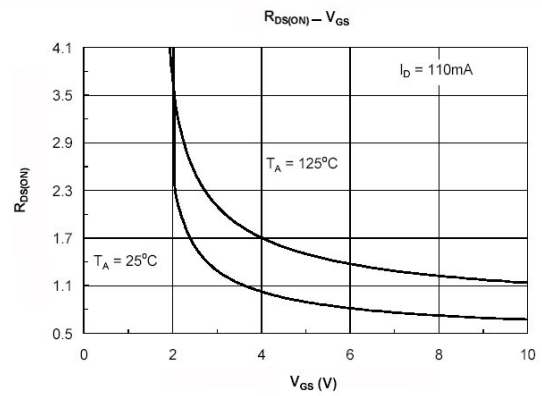
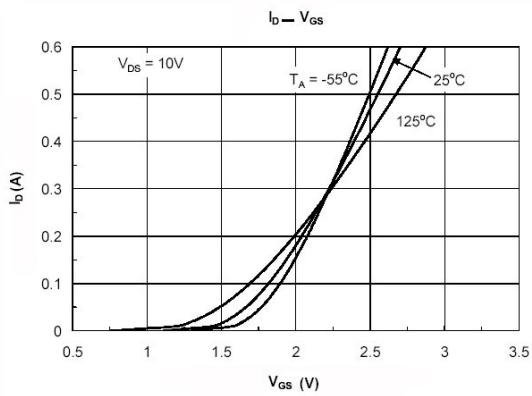
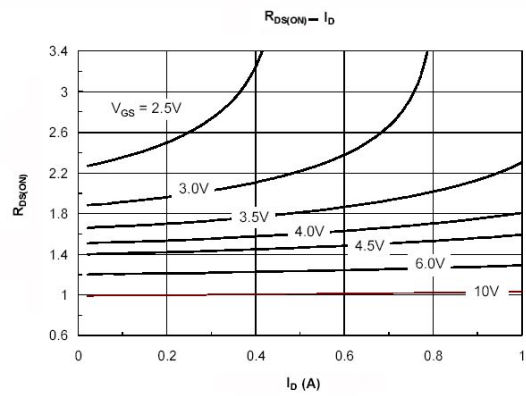
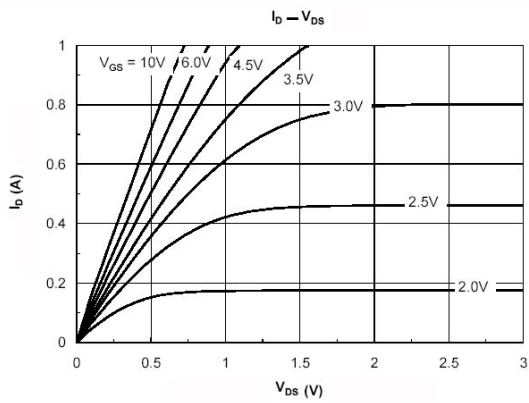
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V_{DSS}	50	V
Gate-Source Voltage	V_{GSS}	±20	V
Drain Current – Continuous	I_D	220	mA
Peak Drain Current	I_{DM}	880	mA
Power Dissipation	P_D	360	mW
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	350	°C/W
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Zero Gate Voltage Drain Current	$I_{DSS(1)}$	$V_{GS}=0$ $V_{DS}=50V$			0.5	μA
	$I_{DSS(2)}$	$V_{GS}=0$ $V_{DS}=30V$			0.1	μA
Gate–Body Leakage.	I_{GSS}	$V_{DS}=0V$ $V_{GS}=\pm 20$			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=1.0mA$	0.8	1.3	1.5	V
Static Drain–Source On–Resistance	$R_{DS(on)(1)}$	$V_{GS}=10V$ $I_D=220mA$		0.7	3.5	Ω
	$R_{DS(on)(2)}$	$V_{GS}=4.5V$ $I_D=220mA$		1.0	6.0	Ω
Forward Transconductance	g_{FS}	$V_{DS}=10V$ $I_D=220mA$	0.12	0.5		S
Drain–Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V$ $I_S=440mA$		0.8	1.4	V
Gate Resistance	R_G	$V_{GS}=15mV$ $f=1.0MHZ$		9		Ω
Turn–On Delay Time	$t_{d(on)}$	$V_{DD}=30V$ $I_D=290mA$ $V_{GS}=10V$ $R_{GEN}=25\Omega$		2.5	5	ns
Turn–On Rise Time	t_r			9	18	ns
Turn–Off Delay Time	$t_{d(off)}$			20	36	ns
Turn–Off Fall Time	t_f			7	14	ns

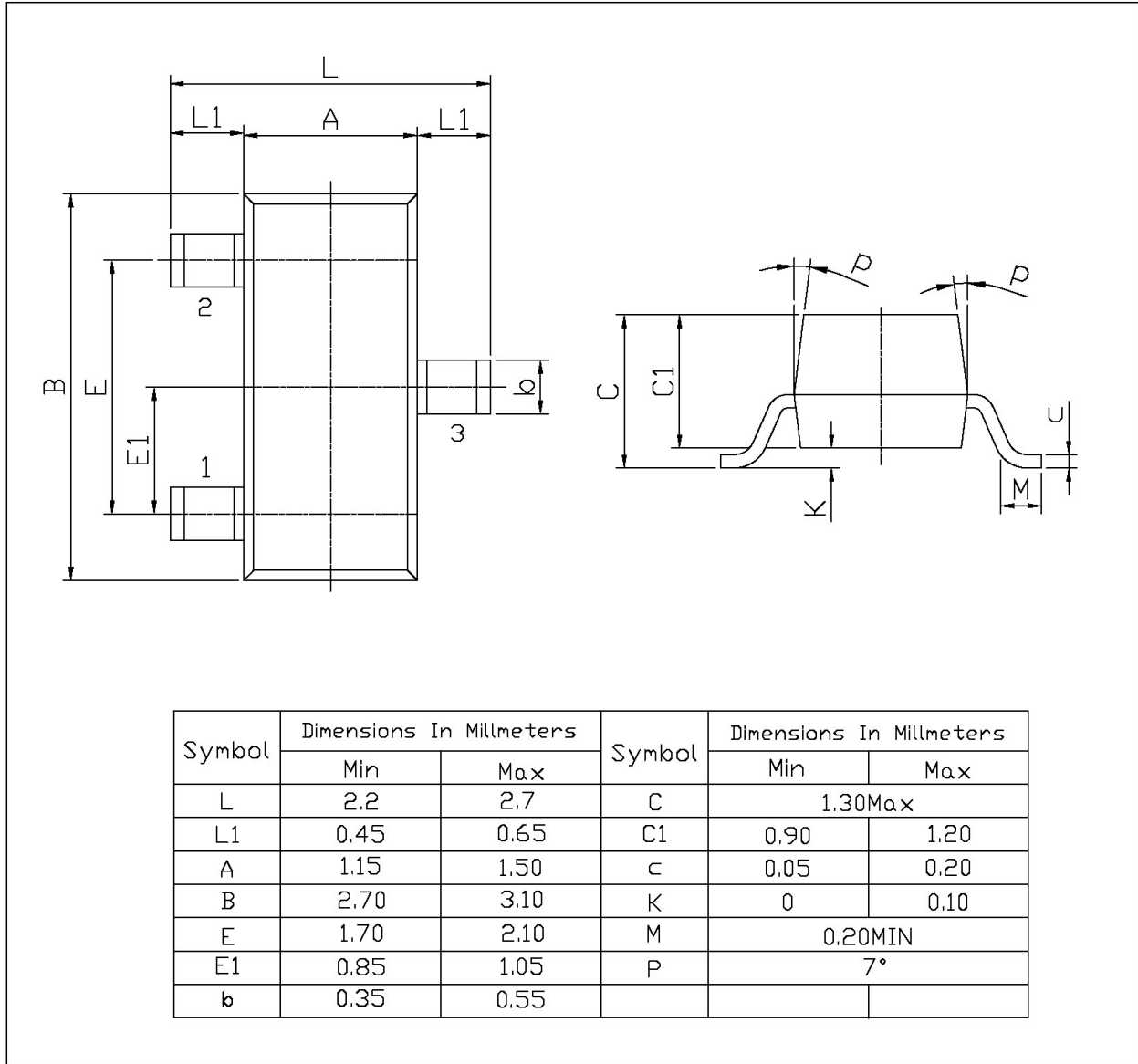
电参数曲线图 / Electrical Characteristic Curve



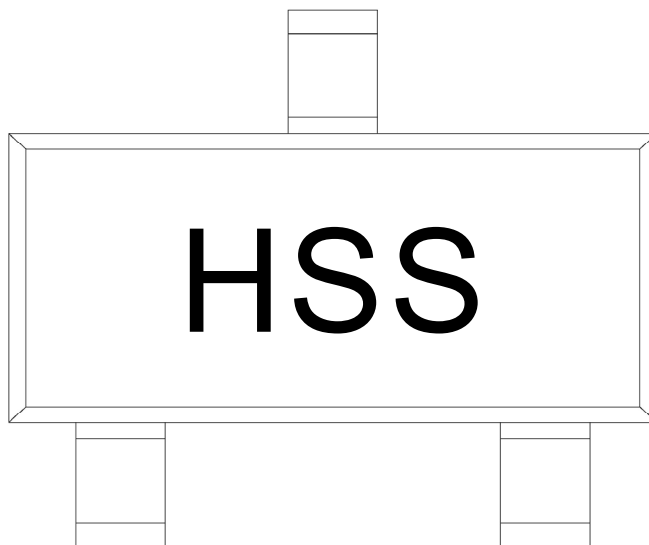
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

H： 为公司代码

SS： 为型号代码

Note:

H: Company Code.

SS: Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	8	240,000	7" ×8	180×120×180	385×257×392

使用说明 / Notices